

Surface Mount Schottky Barrier Diodes

(Pb) Lead(Pb)-Free

Features:

- * Plastic package has Underwriters Laboratory Flammability Classification 94V-0 Utilizing Flame Retardant Epoxy Molding Compound.
- * For surface mounted applications.
- * Exceeds environmental standards of ML-S-19500 / 228
- * Low leakage current

Mechanical Data

- * Case : Molded Plastic, JEDEC SOD-123F / MINI SMA
- * Terminals : Solder Plated, Solderable per ML-STD-750 Method 2026
- * Polarity :Indicated By Cathode Band
- * Mounting Position : Any
- * Weight: 0.04 grams

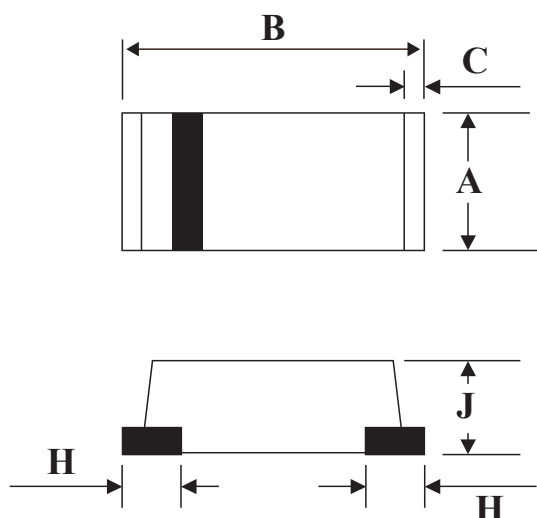
REVERSE VOLTAGE
20-100 Volts
FORWARD CURRENT
2.0 Ampere



MINI-SMA
(SOD-123F)

MINI-SMA Outline Dimension

unit:mm



MINI-SMA		
Dim	Min	Max
A	1.40	1.80
B	3.50	3.90
C	-	0.30(TYP)
H	-	0.70(TYP)
J	1.30	1.70

MAXIMUM RATING

Characteristics	Symbol	B220M	B230M	B240M	B250M	B260M	B280M	B2100M	Unit
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	20	30	40	50	60	80	100	V
Maximum RMS Voltage	V _{RMS}	14	21	28	35	42	56	70	V
Continuous Reverse Voltage	V _R	20	30	40	50	60	80	100	V
Maximum Instantaneous @TA=25 C	V _F	0.5			0.7		0.85		V
Maximum Average Forward (Fig.1)	I _O	2.0							A
Peak Forward Surge Current 8.3 ms Single Half Sine-Wave Superimposed on Rated Load (JEDEC Method)	I _{FSM}	50							A
Maximum DC Reverse Current @TA=25°C At Rated DC Blocking Voltage @TA=125°C	I _R	0.5 10							mA
Typical Thermal Resistance	R _{θJA}	85(TYP)							°C/W
Typical Junction Capacitance	C _J	160(TYP)							pF
Operating Temperature Range	T _J	-55 to+125			-55 to+150				°C
Storage Temperature Range	T _{STG}	-55 to+150							°C

Device Marking

B220M=22 , B230M=23 , B240M=24 , B250M=25 , B260M=26 , B280M=28 , B2100M=20

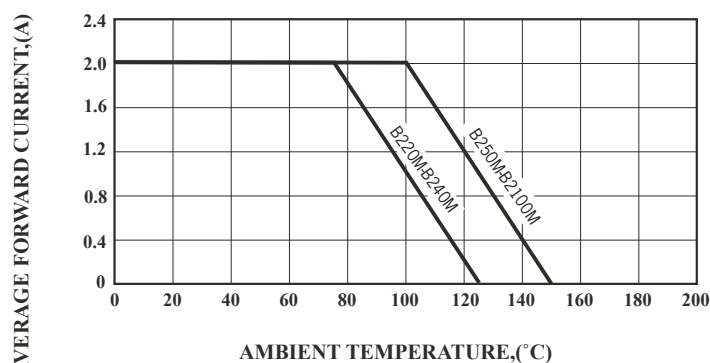


FIG.1 Typical Forward Current Derating Curve

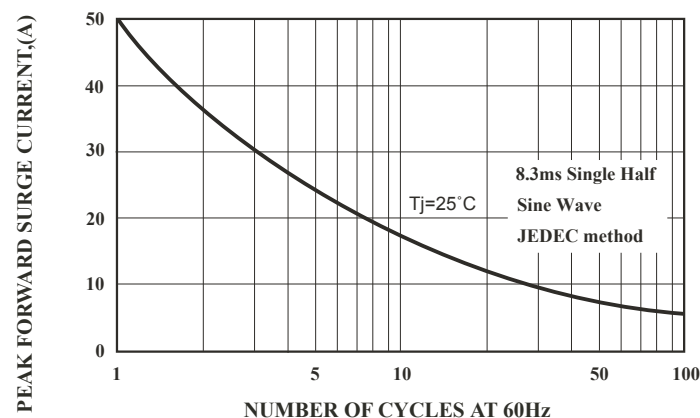


FIG.3 Maximum Non-Repetitive Forward Surge Current

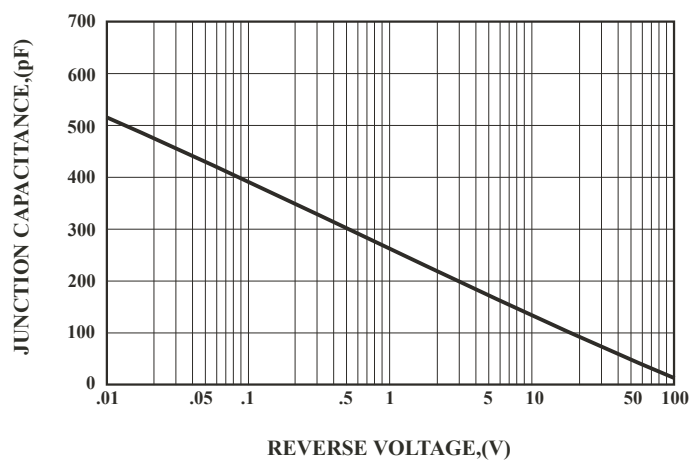


FIG.4 Typical Junction Capacitance

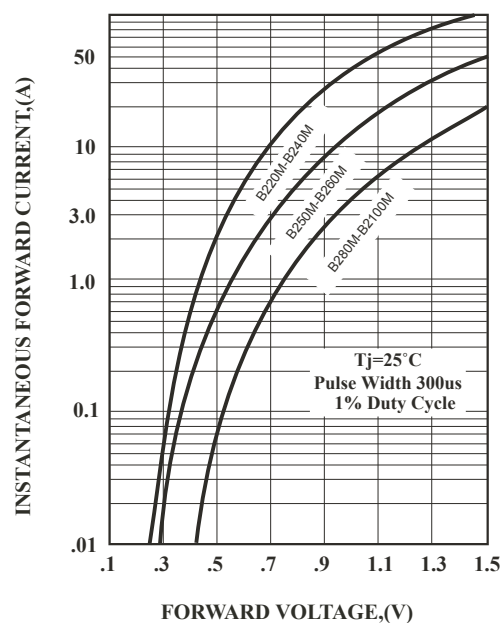


FIG.2 Typical Forward Characteristics

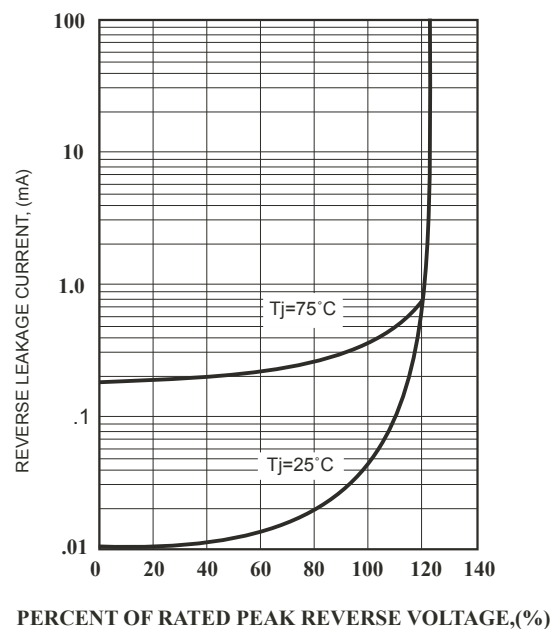


FIG.5 Typical Reverse Characteristics